## MPPS™ Miniature Package Power Solutions 70V PNP LOW SATURATION TRANSISTOR

#### **SUMMARY**

PNP— $V_{CEO}$ = -70V;  $R_{SAT}$  = 117m $\Omega$ ;  $I_{C}$ = -2.5A

#### **DESCRIPTION**

Packaged in the new innovative 2mm x 2mm MLP (Micro Leaded Package) outline, this new 4th generation low saturation PNP transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions.



**MLP322** 

Additionally users gain several other **key benefits**:

Performance capability equivalent to much larger packages Improved circuit efficiency & power levels PCB area and device placement savings Lower Package Height (0.9mm nom) Reduced component count

#### **FEATURES**

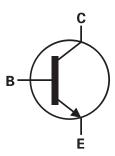
Low Equivalent On Resistance

Extremely Low Saturation Voltage (-220mV max @1A)

h<sub>FE</sub> specified up to 3A

I<sub>C</sub>=2.5A Continuous Collector Current

2mm x 2mm MLP



#### **APPLICATIONS**

DC - DC Converters

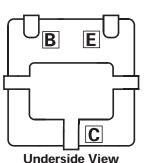
DC - DC Modules

Power switches

Motor control

### ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL	
ZXTD4M322TA	TD4M322TA 7"		3000	
ZXTD4M322TC	13"	8mm	10000	



## **DEVICE MARKING**

**S4** 

ZETEX SEMICONDUCTORS

### **ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	LIMIT	UNIT
Collector-Base Voltage	V <sub>CBO</sub>	-70	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-70	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7.5	V
Peak Pulse Current	I <sub>CM</sub>	-3	А
Continuous Collector Current <sup>(a)</sup>	I <sub>C</sub>	-2.5	А
Base Current	I <sub>B</sub>	-1000	mA
Power Dissipation at TA=25°C <sup>(a)</sup> Linear Derating Factor	P <sub>D</sub>	1.5 12	W mW/°C
Power Dissipation at TA=25°C (b) Linear Derating Factor	P <sub>D</sub>	2.45 19.6	W mW/°C
Power Dissipation at TA=25°C (d) Linear Derating Factor	P <sub>D</sub>	1 8	W mW/°C
Power Dissipation at TA=25°C <sup>(e)</sup> Linear Derating Factor	P <sub>D</sub>	3 24	W mW/°C
Operating & Storage Temperature Range	T <sub>j</sub> :T <sub>stg</sub>	-55 to +150	°C
Junction Temperature	Tj	150	°C

### THERMAL RESISTANCE

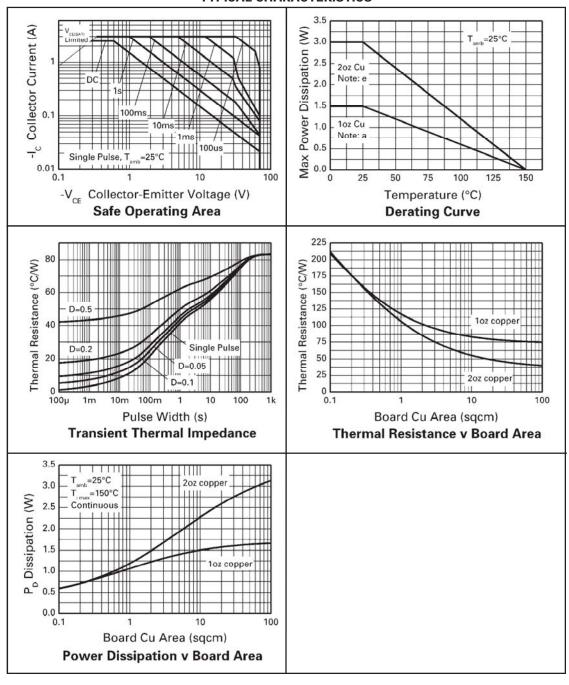
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient <sup>(a)</sup>	$R_{\Theta JA}$	83	°C/W
Junction to Ambient <sup>(b)</sup>	$R_{\Theta JA}$	51	°C/W
Junction to Ambient <sup>(d)</sup>	$R_{\Theta JA}$	125	°C/W
Junction to Ambient <sup>(e)</sup>	$R_{\Theta JA}$	42	°C/W

#### NOTES

- (a) For a single device surface mounted on 10 sq cm 1oz copper on FR4 PCB, in still air conditions with all exposed pads attached.
- (b) For a single device surface mounted on 10 sq cm 1oz copper on FR4 PCB, in still air conditions measured at t≤5 secs **with all exposed pads attached**.
- $\label{eq:constraint} \textbf{(c) Repetitive rating pulse width limited by max junction temperature. Refer to Transient Thermal Impedance graph.} \\$
- (d) For a single device surface mounted on 10 sq cm 1oz copper FR4 PCB, in still air conditions with minimal lead connections only.
- (e) For a single device surface mounted on 65 sq cm 2oz copper FR4 PCB, in still air conditions with all exposed pads attached.
- (f) The minimum copper dimensions required for mounting are no smaller than the exposed metal pads on the base of the device, as shown in the package dimensions data. The thermal resistance for a device mounted on 1.5mm thick FR4 board using minimum copper of 1oz weight and 1mm wide tracks is Rth= 300°C/W giving a power rating of Ptot=420mW



## **TYPICAL CHARACTERISTICS**





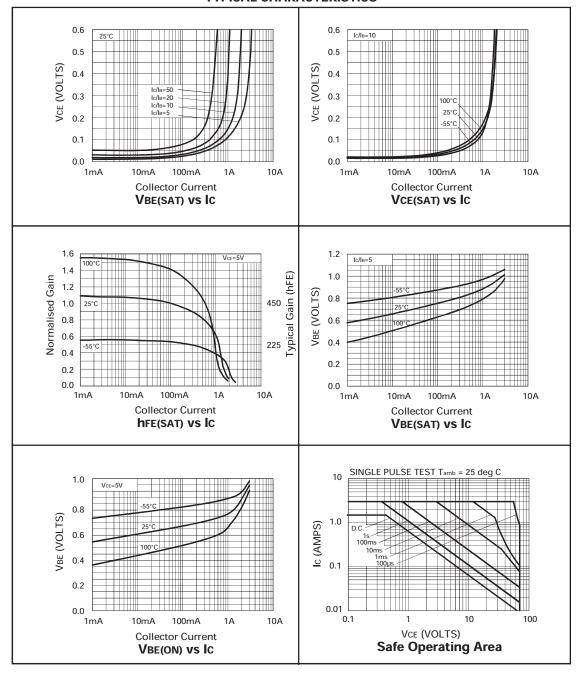
## **ELECTRICAL CHARACTERISTICS** (at T<sub>amb</sub> = 25°C unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS	
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-70	-150		V	I <sub>C</sub> =-100μA	
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-70	-125		V	I <sub>C</sub> =-10mA*	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-7.5	-8.5		V	I <sub>E</sub> =-100μA	
Collector Cut-Off Current	I <sub>CBO</sub>			-25	nA	V <sub>CB</sub> =-55V	
Emitter Cut-Off Current	I <sub>EBO</sub>			-25	nA	V <sub>EB</sub> =-6V	
Collector Emitter Cut-Off Current	I <sub>CES</sub>			-25	nA	V <sub>CE</sub> =-55V	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>		-35 -135 -140 -175	-50 -200 -220 -260	mV mV mV	I <sub>C</sub> =-0.1A, I <sub>B</sub> =-10mA* I <sub>C</sub> =-0.5A, I <sub>B</sub> =-20mA* I <sub>C</sub> =-1A, I <sub>B</sub> =-100mA* I <sub>C</sub> =-1.5A, I <sub>B</sub> =-200mA*	
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>		-0.94	-1.05	V	I <sub>C</sub> =-1.5A, I <sub>B</sub> =-200mA*	
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>		-0.78	-1.00	V	I <sub>C</sub> =-1.5A, V <sub>CE</sub> =-5V*	
Static Forward Current Transfer Ratio	h <sub>FE</sub>	300 300 175 40	470 450 275 60 10			I <sub>C</sub> =-10mA, V <sub>CE</sub> =-5V* I <sub>C</sub> =-100mA, V <sub>CE</sub> =-5V* I <sub>C</sub> =-1A, V <sub>CE</sub> =-5V* I <sub>C</sub> =-1.5A, V <sub>CE</sub> =-5V* I <sub>C</sub> =-3A, V <sub>CE</sub> =-5V*	
Transition Frequency	f <sub>T</sub>	150	180		MHz	I <sub>C</sub> =-50mA, V <sub>CE</sub> =-10V f=100MHz	
Output Capacitance	C <sub>obo</sub>		14	20	pF	V <sub>CB</sub> =-10A, f=1MHz	
Turn-On Time	t <sub>(on)</sub>	1 1 1		ns	V <sub>CC</sub> =-50V, I <sub>C</sub> =-1A		
Turn-Off Time	t <sub>(off)</sub>		700		ns	I <sub>B1</sub> =I <sub>B2</sub> =-50mA	

<sup>\*</sup>Measured under pulsed conditions. Pulse width=300  $\mu s.$  Duty cycle  $\leq 2\%$ 

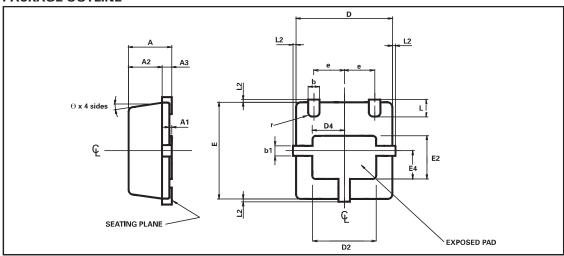


## **TYPICAL CHARACTERISTICS**





## **PACKAGE OUTLINE**



Controlling dimensions are in millimetres. Approximate conversions are given in inches

## **PACKAGE DIMENSIONS**

DIM	Millin	netres	Inc	hes	DIM	Millimetres		Inches	
DIIVI	Min	Max	Min	Max	DIIVI	Min	Max	Min	Max
Α	0.80	1.00	0.0315	0.0393	е	0.65 REF		0.0255 REF	
A1	0.00	0.05	0.00	0.002	E	2.00 BSC		0.0787	
A2	0.65	0.75	0.0255	0.0295	E2	0.79	0.99	0.031	0.039
А3	0.15	0.25	0.0059	0.0098	E4	0.48	0.68	0.0188	0.0267
b	0.18	0.28	0.0070	0.0110	L	0.20	0.45	0.0078	0.0177
b1	0.17	0.30	0.0066	0.0118	L2	0.125 MAX.		0.005 REF	
D	2.00	BSC	0.078	7 BSC	r	0.075 BSC		0.002	9 BSC
D2	1.22	1.42	0.0480	0.0559	θ	0°	12°	0°	12°
D4	0.56	0.76	0.0220	0.0299					

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